

SOT715-1

plastic low profile fine-pitch ball grid array package; 216 balls; body 16 x 16 x 1.05 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA216
Package type industry code	LFBGA216
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-205
Mounting method type	S (surface mount)
Issue date	14-11-2001

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		15.9	-	16	16.1	mm
E	package width		15.9	-	16	16.1	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		0.95	-	1.05	1.2	mm
n ₂	actual quantity of termination		-	-	216	-	



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2. Package outline

LFBGA216: plastic low profile fine-pitch ball grid array package; 216 balls; body 16 x 16 x 1.05 mm SOT715-1

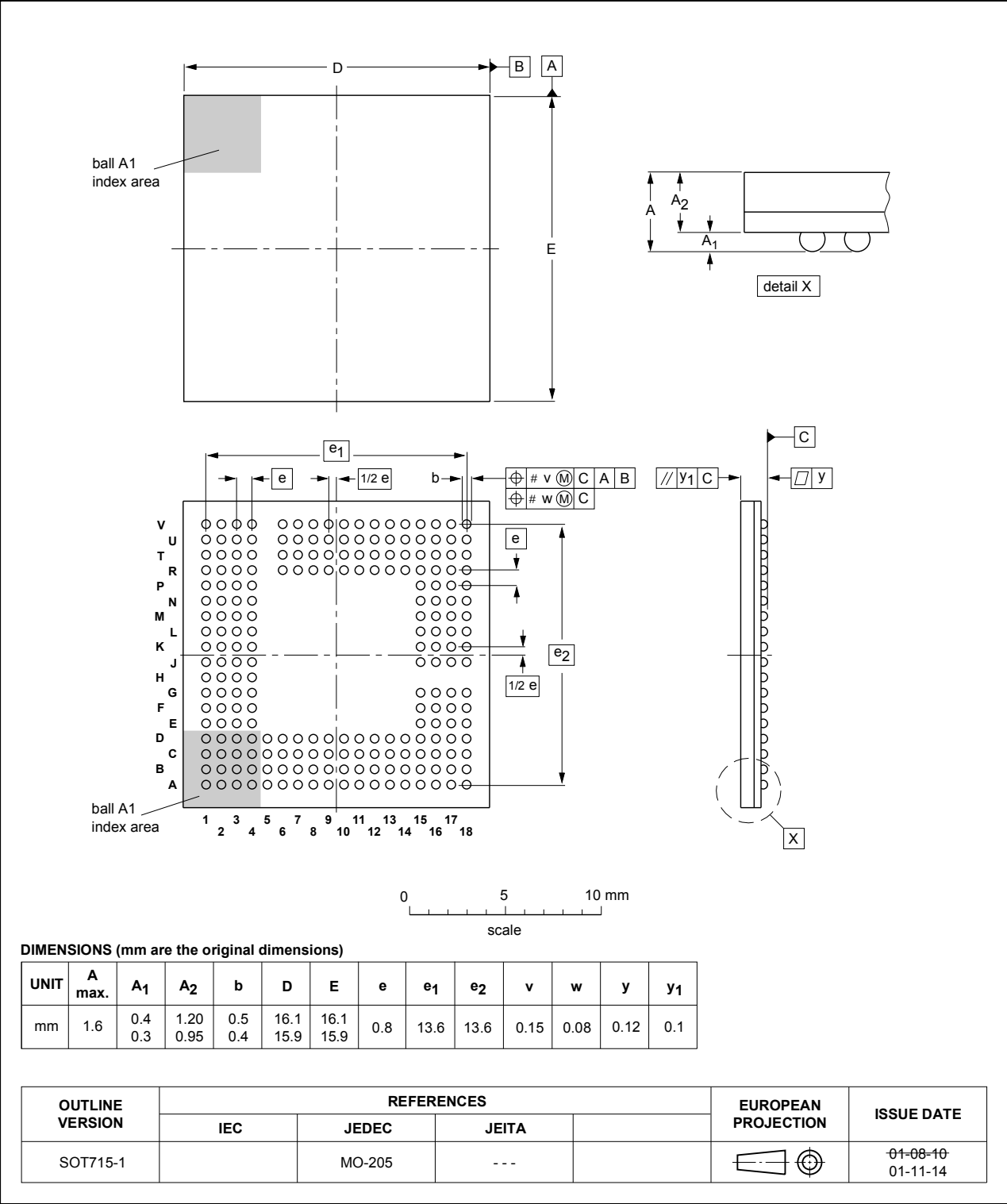


Fig. 1. Package outline LFBGA216 (SOT715-1)

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3. Soldering

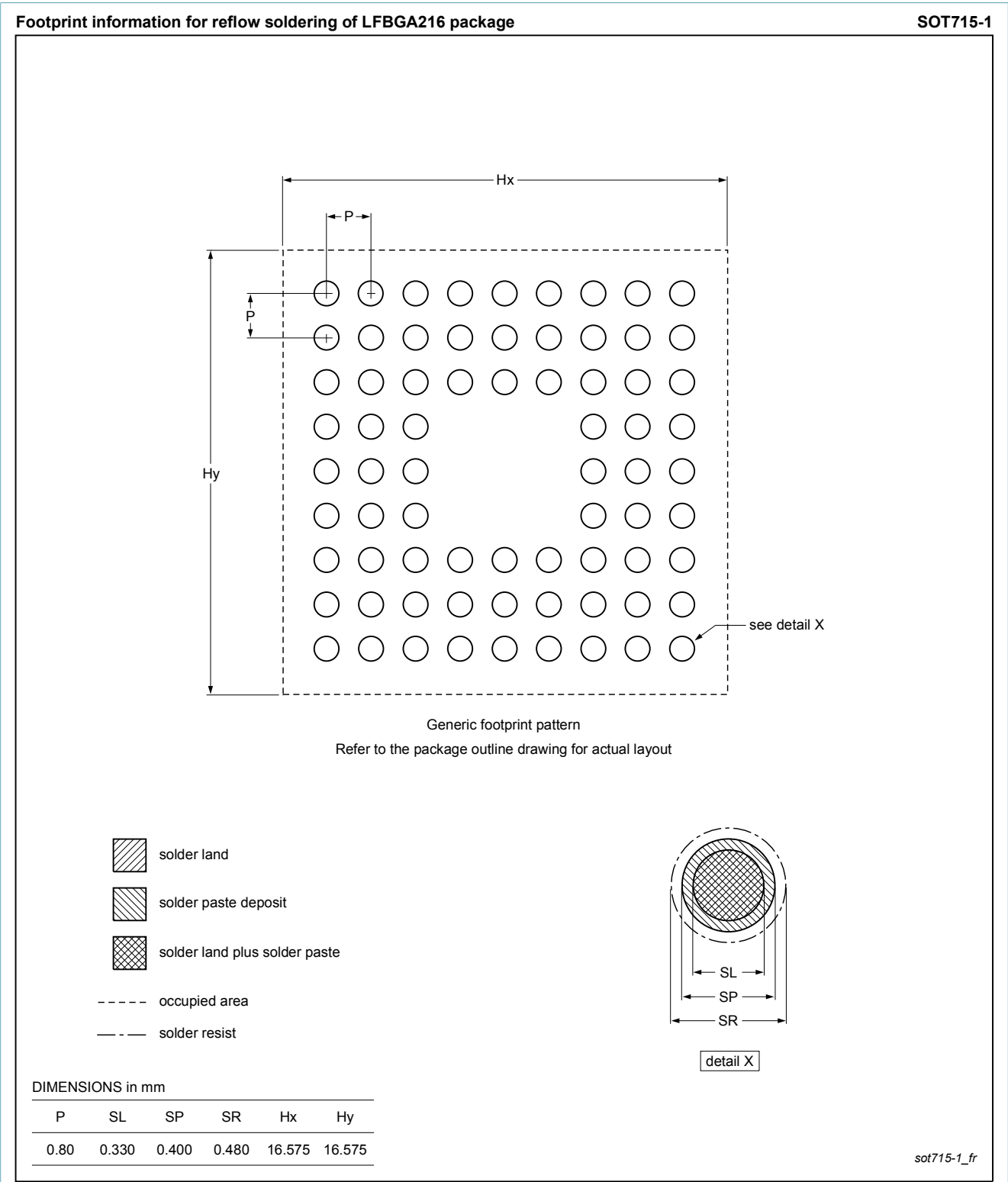


Fig. 2. Reflow soldering footprint for LFBGA216 (SOT715-1)

4. Legal information

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